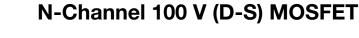
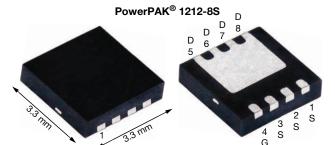
SiSS46DN

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Top View

Bottom View

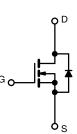
PRODUCT SUMMARY				
V _{DS} (V)	100			
$R_{DS(on)}$ max. (Ω) at V_{GS} = 10 V	0.0128			
$R_{DS(on)}$ max. (Ω) at V_GS = 7.5 V	0.0146			
Q _g typ. (nC)	21.5			
I _D (A)	45.3			
Configuration	Single			

FEATURES

- TrenchFET[®] Gen IV power MOSFET
- Very low R_{DS} Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} Q_{oss} FOM
- 100 % R_{α} and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Synchronous rectification
- Primary side switch
- DC/DC converter
- Solar micro inverter
- Motor drive switch
- Battery and load switch
- Industrial



ROHS COMPLIANT

HALOGEN

FREE

N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK 1212-8S
Lead (Pb)-free and halogen-free	SiSS46DN-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, un PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	100	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		45.3		
	T _C = 70 °C		36.2		
	T _A = 25 °C	I _D	12.5 ^{b, c}		
	T _A = 70 °C	1	10 ^{b, c}	•	
Pulsed drain current (t = 100 μs)		I _{DM}	100	— A	
Continuous source-drain diode current	T _C = 25 °C		59.7		
	T _A = 25 °C	I _S	4.5 ^{b, c}		
Single pulse avalanche current		I _{AS}	20		
gle pulse avalanche energy L = 0.1 mH		E _{AS}	20	mJ	
Maximum power dissipation	T _C = 25 °C		65.7		
	T _C = 70 °C		42	14/	
	T _A = 25 °C	P _D	5 b, c	W	
	T _A = 70 °C	1 -	3.2 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	**	
Soldering recommendations (peak temperature) c		Ĭ	260	°C	

THERMAL RESISTANCE RATINGS

PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	20	25	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.5	1.9	0/10	

Notes

a. Package limited

b. Surface mounted on 1" x 1" FR4 board

c. t = 10 s

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

f. Maximum under steady state conditions is 63 °C/W

g. $T_C = 25 \ ^{\circ}C$

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d. See solder profile (<u>www.vishav.com/doc?73257</u>). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

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SiSS46DN Vishay Siliconix

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			•			•	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	100	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA		57	-		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-7.1	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2	-	3.4	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	100	nA	
Zero gate voltage drain current	I _{DSS} -	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	μA	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15		
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30	-	-	A	
	_	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ $V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	0.0106	0.0128	Ω	
Drain-source on-state resistance ^a	R _{DS(on)}		-	0.0112	0.0146		
Forward transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 10 A	-	50	-	S	
Dynamic ^b			•			•	
Input capacitance	C _{iss}		-	2140	-	pF	
Output capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	-	161	-		
Reverse transfer capacitance	C _{rss}		-	14	-		
Tababa ata ata ata a	0	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$	-	28	42	42 33 - nC - -	
Total gate charge	Qg	V _{DS} = 50 V, V _{GS} = 6 V, I _D =10 A	-	21.5	33		
Gate-source charge	Q _{gs}		-	8.8	-		
Gate-drain charge	Q _{qd}		-	4.2	-		
Output charge	Q _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$	-	28.9	-		
Gate resistance	Rg	f = 1 MHz	0.3	0.85	1.5	Ω	
Turn-on delay time	t _{d(on)}		-	12	26		
Rise time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_{L} = 5 \Omega, \text{ I}_{D} \cong 10 \text{ A},$	-	6	12		
Turn-off delay time	t _{d(off)}	$V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	21	42	1	
Fall time	t _f		-	6	12		
Turn-on delay time	t _{d(on)}		-	15	30	ns	
Rise time	tr	$\label{eq:VDD} \begin{split} V_{DD} &= 50 \text{ V}, \text{R}_{\text{L}} = 5 \Omega, \text{I}_{\text{D}} \cong 10 \text{A}, \\ V_{\text{GEN}} &= 7.5 \text{V}, \text{R}_{\text{g}} = 1 \Omega \end{split}$	-	7	14		
Turn-off delay time	t _{d(off)}		-	19	38		
Fall time	t _f		-	7	14		
Drain-Source Body Diode Characteristi	cs		•			•	
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	59.7		
Pulse diode forward current	I _{SM}		-	-	100	A	
Body diode voltage	V _{SD}	I _S = 5 A, V _{GS} = 0 V	-	0.77	1.1	V	
Body diode reverse recovery time	t _{rr}		-	40	80	ns	
Body diode reverse recovery charge	Q _{rr}	I _F = 10 A, di/dt = 100 A/μs,	-	61	122	nC	
Reverse recovery fall time	ta	$T_J = 25 \text{°C}$	-	33	-		
Reverse recovery rise time	t _b		-	7		ns	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

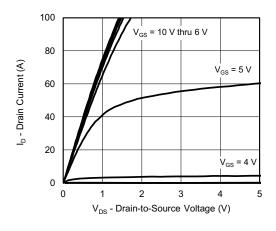
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

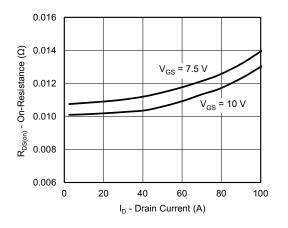
2



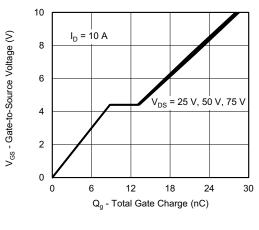
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



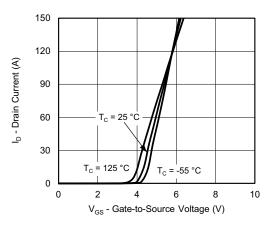
Output Characteristics



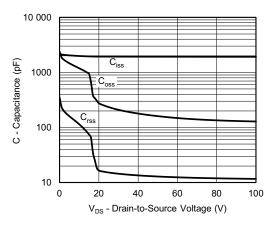
On-Resistance vs. Drain Current and Gate Voltage



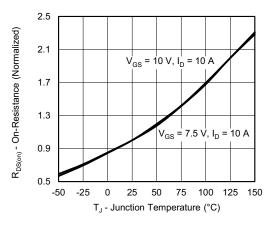
Gate Charge



Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

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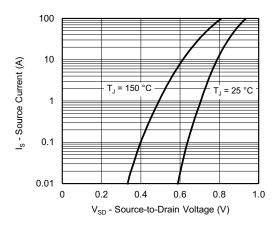
3

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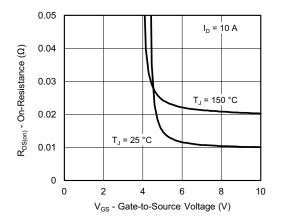
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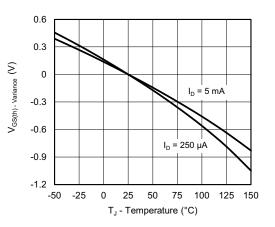
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



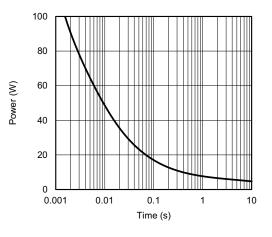
Source-Drain Diode Forward Voltage



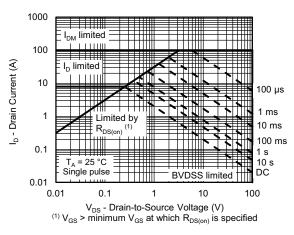
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

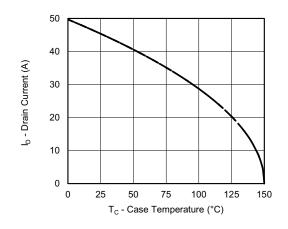


Safe Operating Area, Junction-to-Ambient

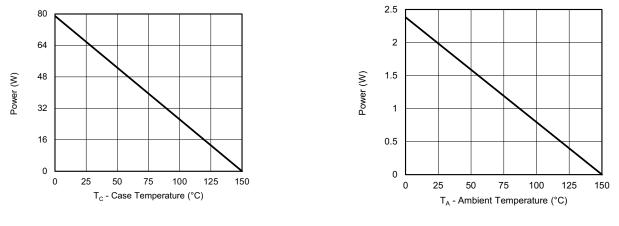
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating a



Power, Junction-to-Case

Power, Junction-to-Ambient

Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

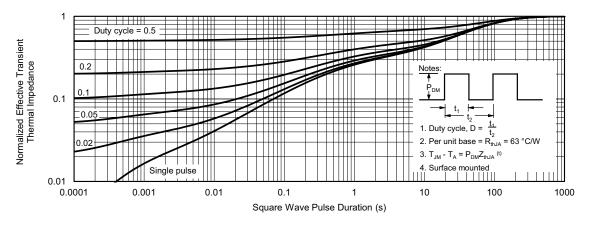
5



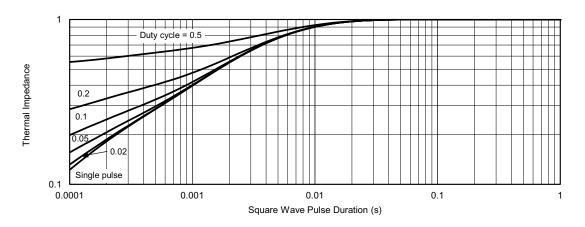
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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